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Centerline (Pitch): .5 mm [ .02 in ]

PCB Mount Orientation: **Right Angle**

Contact Mating Location: **Bottom**

Termination Method to PCB: **Surface Mount**

FPC Actuator Type: **Front Flip-Lock**

Features

Product Type Features

|                                   |                                                       |
|-----------------------------------|-------------------------------------------------------|
| PCB Connector Type                | PCB Mount Receptacle                                  |
| Connector & Contact Terminates To | Flexible Printed Circuit (FPC), Printed Circuit Board |
| Connector Product Type            | Connector Assembly                                    |
| Connector System                  | Flex-to-Board                                         |
| FPC Actuator Type                 | Front Flip-Lock                                       |

Configuration Features

|                                   |             |
|-----------------------------------|-------------|
| Compatible With Wire & Cable Type | FFC, FPC    |
| Number of Rows                    | 1           |
| PCB Mount Orientation             | Right Angle |
| Number of Positions               | 5           |

Electrical Characteristics

|                   |         |
|-------------------|---------|
| Operating Voltage | 250 VAC |
|-------------------|---------|

Body Features

|                       |         |
|-----------------------|---------|
| Primary Product Color | Natural |
|-----------------------|---------|



Contact Features

|                                                         |                 |
|---------------------------------------------------------|-----------------|
| Contact Current Rating (Max)                            | .5 A            |
| Contact Shape & Form                                    | Single Beam     |
| PCB Contact Termination Area Plating Material Thickness | .025 µm[1 µin]  |
| Contact Layout                                          | Inline          |
| Contact Base Material                                   | Phosphor Bronze |
| PCB Contact Termination Area Plating Material           | Gold            |
| Contact Type                                            | Socket          |
| Contact Mating Area Plating Material Thickness          | .025 µm[1 µin]  |
| Contact Mating Location                                 | Bottom          |
| Contact Mating Area Plating Material                    | Gold (Au)       |

Termination Features

|                           |               |
|---------------------------|---------------|
| Termination Method to PCB | Surface Mount |
|---------------------------|---------------|

Mechanical Attachment

|                         |             |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
| Mating Alignment        | With        |
| PCB Mount Retention     | With        |
| PCB Mount Alignment     | Without     |

Housing Features

|                    |               |
|--------------------|---------------|
| Housing Material   | LCP           |
| Centerline (Pitch) | .5 mm[.02 in] |

Dimensions

|                              |                  |
|------------------------------|------------------|
| Connector Width              | 6.25 mm[.246 in] |
| Accepts Flex Cable Thickness | .3 mm[.012 in]   |
| Connector Height             | 2 mm[.079 in]    |
| Connector Length             | 7.25 mm[.285 in] |

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Identification Marking

|                                |      |
|--------------------------------|------|
| Circuit Identification Feature | With |
|--------------------------------|------|

Packaging Features

|                  |             |
|------------------|-------------|
| Packaging Method | Tape & Reel |
|------------------|-------------|



Packaging Quantity2000

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                                |
|-----------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                      |
| EU ELV Directive 2000/53/EC                   | Not Yet Reviewed                                                                                                               |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                        |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2025 (250)<br>Candidate List Declared Against: JAN 2022 (223)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC Free                                               |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                 |

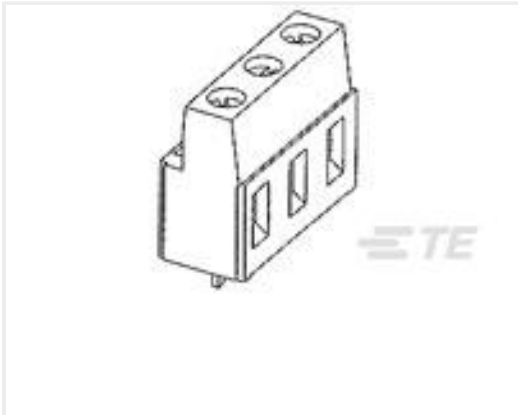
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



TE Part #5-146281-6  
06 MODII HDR SRST B/A .100CL



TE Part #282845-3  
TERM-BLOK,PCB MNT,90DG,3P,7.62



TE Part #5-520315-3  
TRIOMATE ASSY V 3P L=3.556LDFR



TE Part #2-1445100-8  
MICRO MNL HDR ASSY S/ROW LF



TE Part #1-1734248-1  
1.0 FPC, ZIF V/T, SMT, 11P



TE Part #2118717-2  
STD SHIELD COVER, CRS-26.71X26.71X2.00MM



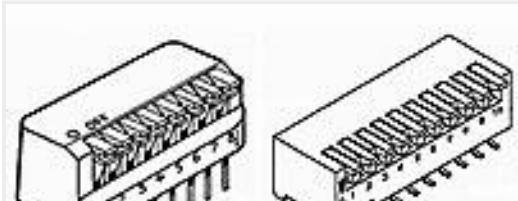
TE Part #3-2176325-1  
CRGP 0402 3K3 1%



TE Part #3-2176325-8  
CRGP 0402 12K 1%



TE Part #2-1734592-9  
FPC CONN. 0.5MM PITCH B/C, 29P



TE Part #1-5435802-7  
RIGHT ANGLE DIP SW 6 P SEALED

Documents

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1775333-5\_F.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_1775333-5\_F.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1775333-5\_F.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

ZIF 0.5mm Pitch FPC, SMT Connector

English